

4H-SiC devices simulation with DEVSIM

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Why 4H-SiC ?

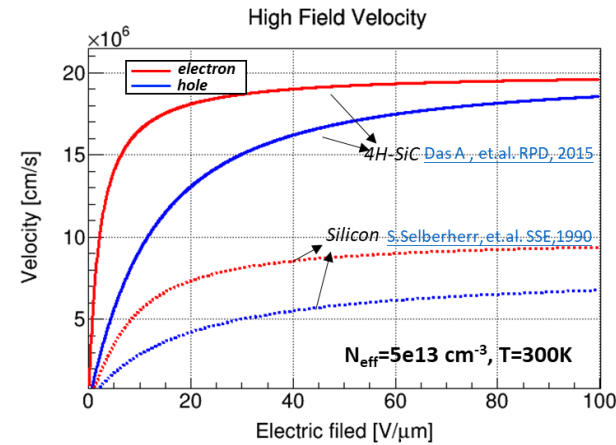
Silicon & 4H-SiC

Characteristic	Si	4H-SiC
E_g (eV)	1.12	3.26
Thermal conductivity	1.5	4.9
$E_{breakdown}$ (V/cm)	0.5	3
Saturated electron velocity (cm/s)	1×10^7	2×10^7
ionization energy for e-h pair (eV)	3.64	7.8
displacement energy	13	21.8

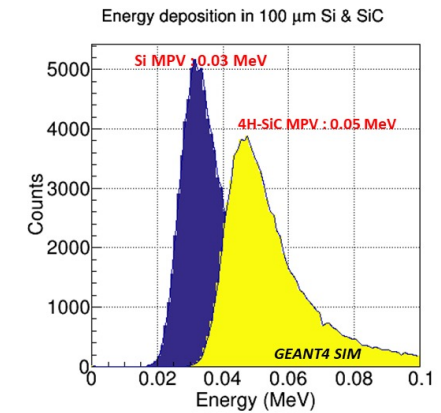


- ✓ High radiation hardness
- ✓ Low dark current
- ✓ high temperature resistance
- ✓ High saturated carrier velocity -> fast response

Potential application for fast MIPs detection



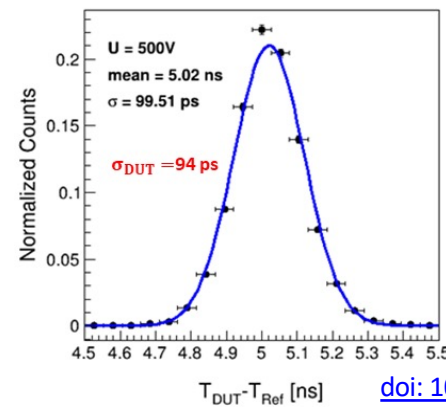
Saturated Carrier Velocity: 4H-SiC > Silicon



~ 55 e-h pairs/ μ m for MIPs in SiC

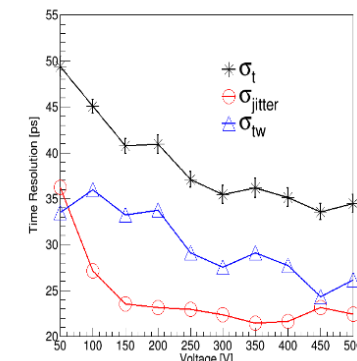
Good time resolution of 4H-SiC detector

100 μ m 4H-SiC PIN for MIPs (measurement)



doi: 10.3389/fphy.2022.718071

3D 4H-SiC Detector for MIPs (simulation)



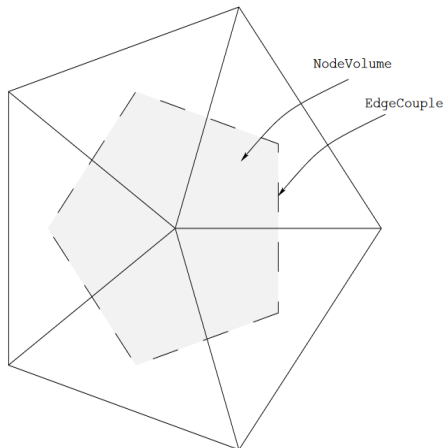
doi: 10.3390/mi13010046

Introduction of DEVSIM

- ◆ DEVSIM is a TCAD device simulation package written in C++, with a Python front end. It is capable for simulating 1D, 2D, 3D structures with models describing advanced physical effects <https://devsim.org/>
- ◆ DEVSIM uses the control volume approach for assembling partial-differential equations (PDE's)

◆ Node model

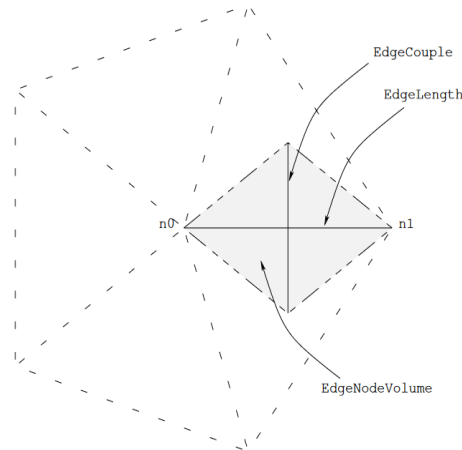
- The simplest model
- Represents the solution variables being solved for



$n, p, \varphi \dots$

◆ Edge model

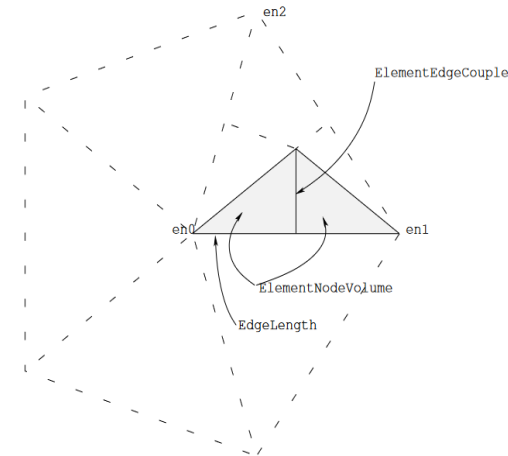
- Reference node models defined on the ends of the edge
- The two nodes on the edge, n_0 and n_1



$E(\varphi) \dots$

◆ Element Edge model

- Cannot be specified on both nodes of the edge,
- The three nodes on each triangle edge and are denoted as $en_0, en_1, \text{ and } en_2$



$\mu_n(E), \mu_p(E) \dots$

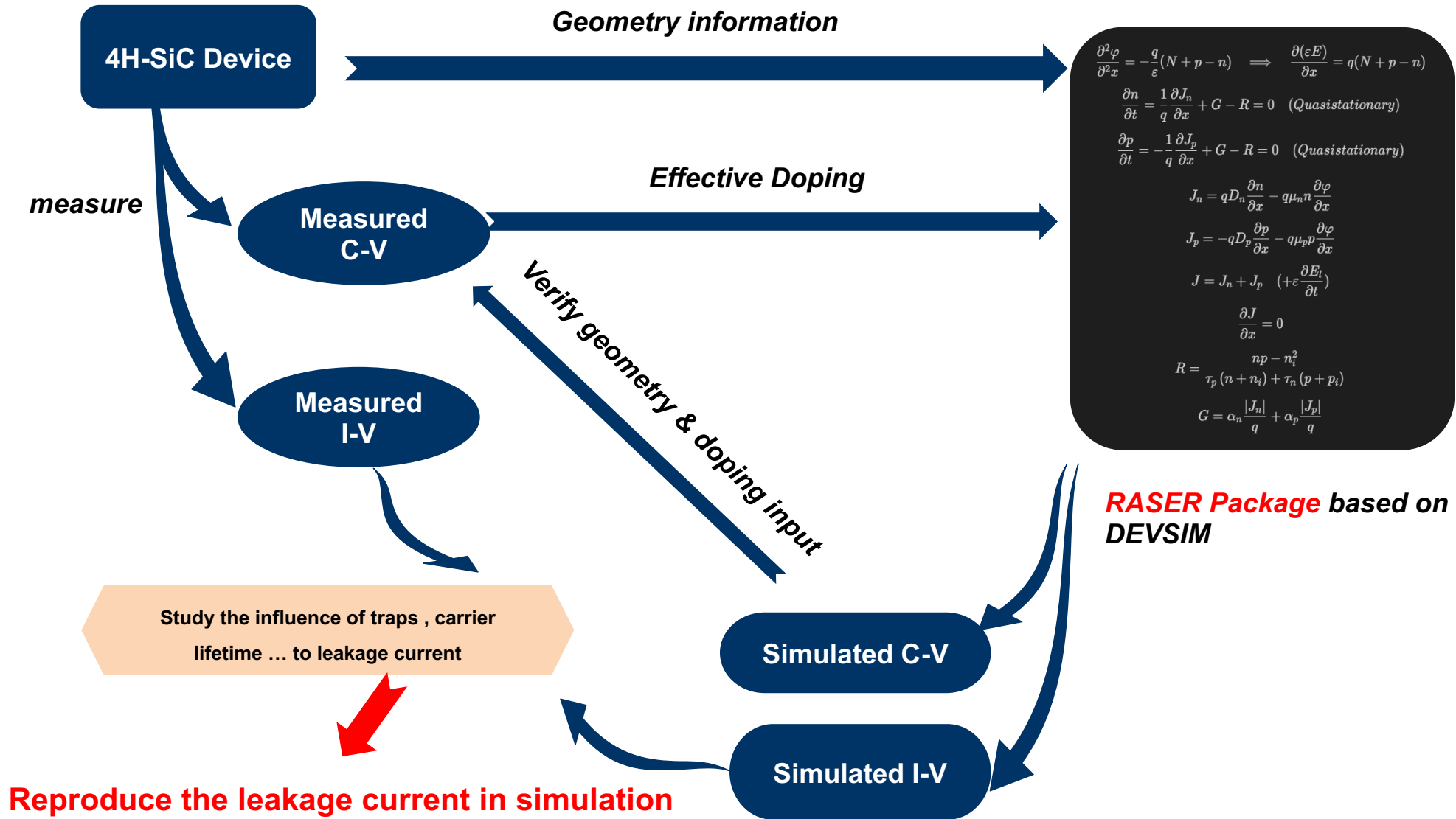
Advantages:

- ◆ Open Source;
- ◆ Strong expandability;
- ◆ Easily interact with Gennt4 for detector simulation;

Drawbacks:

- ◆ Finite element physical equations written by users

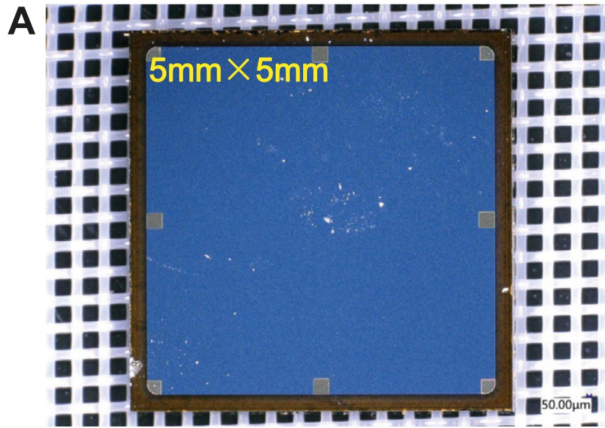
Simulation roadmap



4H-SiC PIN under study

A time resolution $\sigma_T=94\text{ps}$ indicates 4H-SiC sensor has potential application of fast MIPs detection.

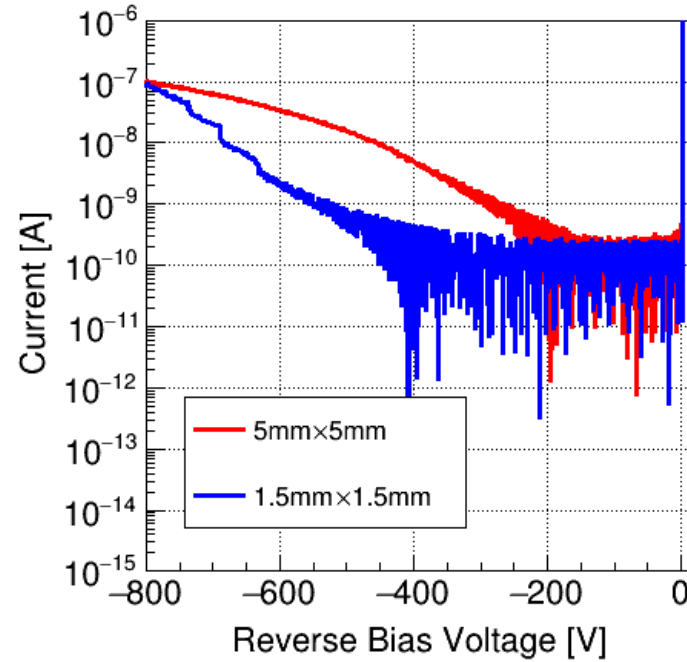
Geometry



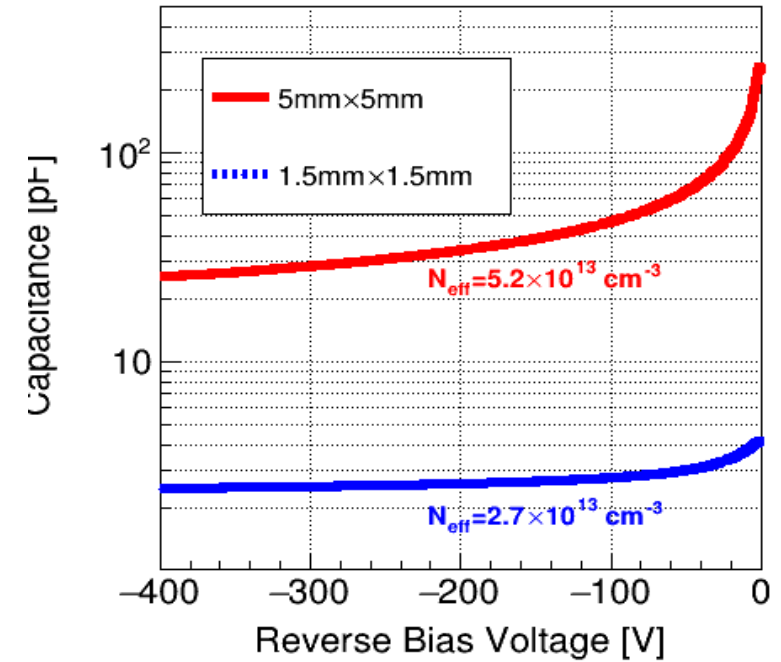
B

Au 1μm	Passivation layer	Au 1μm
Ni 75nm		
Imp P+		
100μm N- epi		
350μm N+ 4H-SiC sub		
Ni 75nm		
Ti/Al/Au 1.5μm		

I-V performance



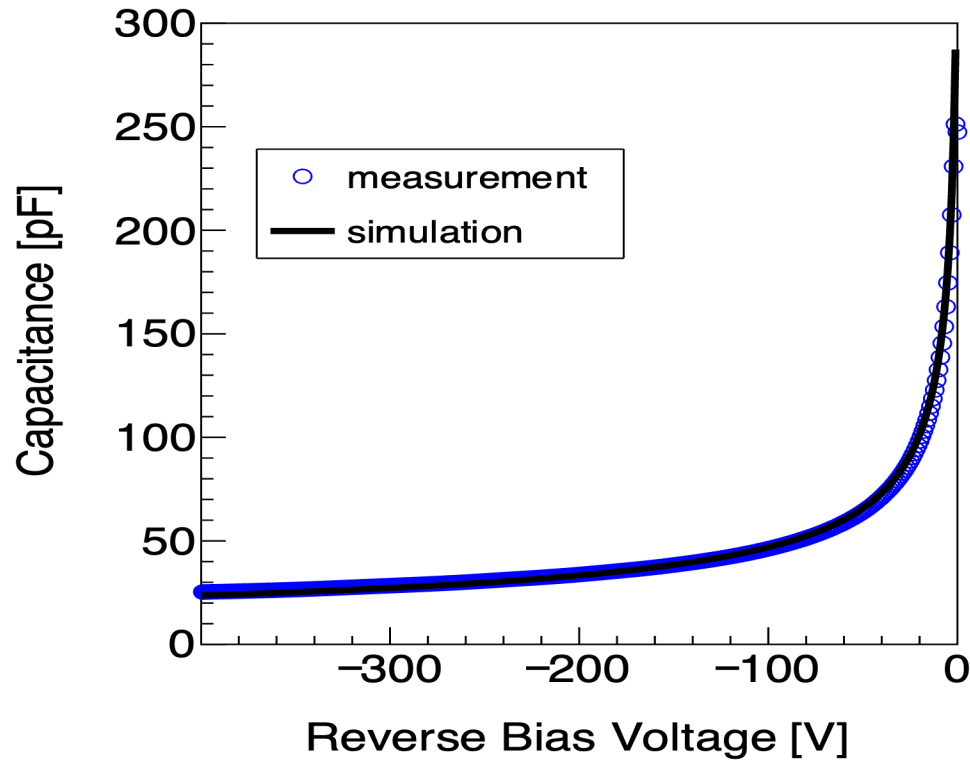
C-V performance



The NJU 100 μm PIN with 5mm*5mm size as device to study.

[10.3389/fphy.2022.718071](https://doi.org/10.3389/fphy.2022.718071)

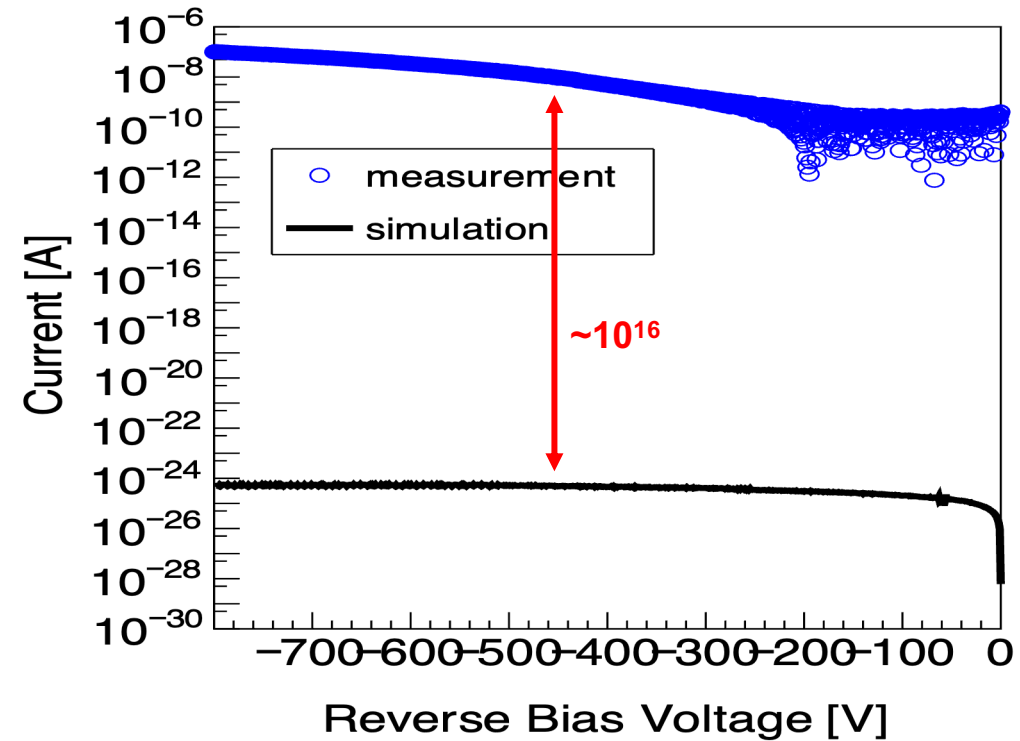
C-V performance & simulation



◆ **Good agreement** between measurement and simulation!

◆ Verify the geometry & doping input to SICAR is correct.

I-V performance & simulation



◆ **Large discrepancy** between measurement and simulation!

◆ The influence of **Carrier Recombination & Generation** to leakage current should be considered.

Shockley-Read-Hall G&R to Leakage Current

Recombination

$$R = R_{SRH} + R_{Trap} + \dots$$

$$R_{net}^{SRH} = \frac{np - n_{i,eff}^2}{\tau_p(n + n_1) + \tau_n(p + p_1)}$$

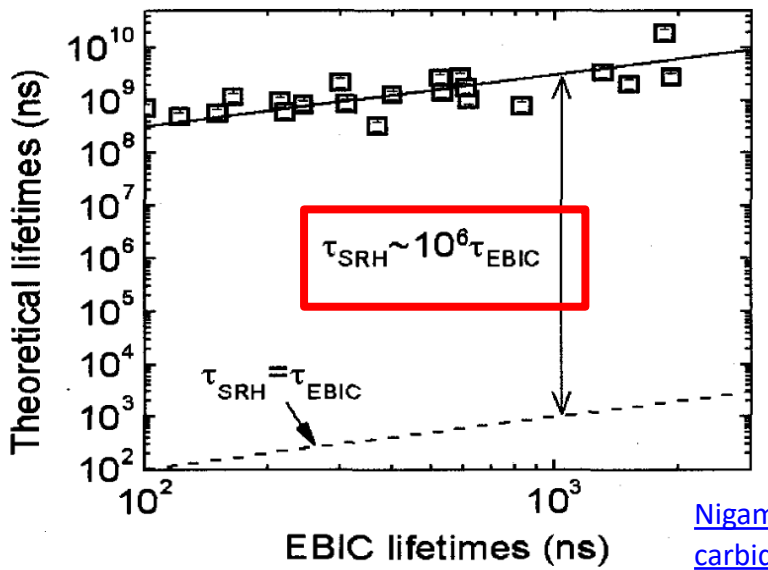
$$n_1 = n_{i,eff} \exp\left(\frac{E_{trap}}{kT}\right)$$

$$p_1 = n_{i,eff} \exp\left(\frac{-E_{trap}}{kT}\right)$$

Default carrier lifetime:

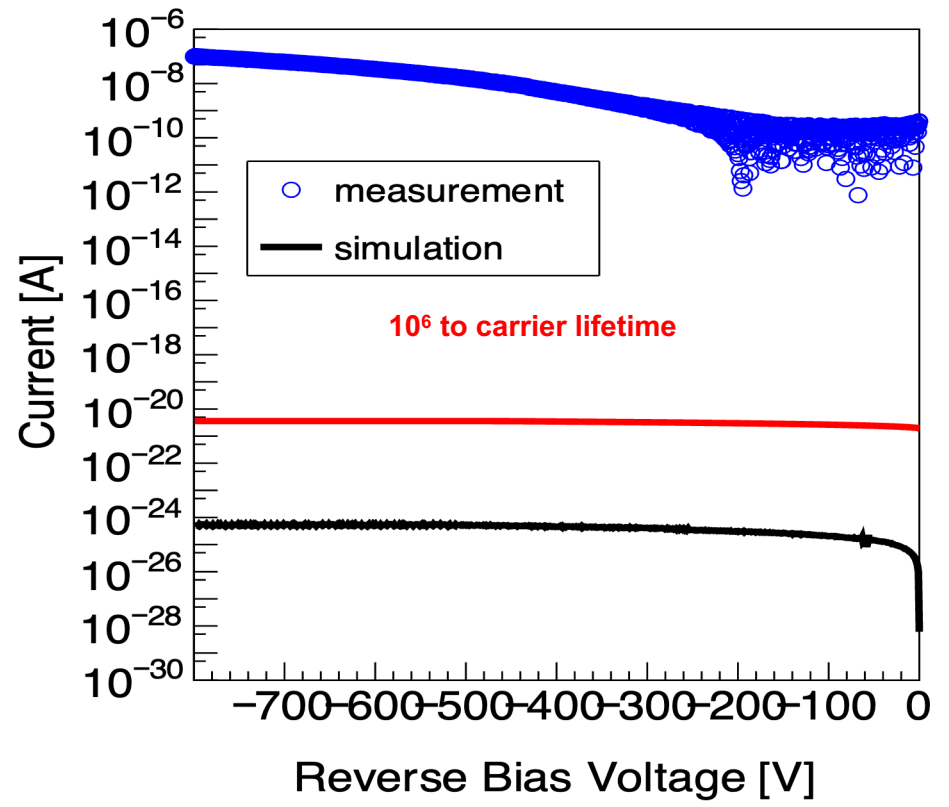
$$\tau_n = 2.5 \times 10^{-6} \text{ s}$$

$$\tau_p = 0.5 \times 10^{-6} \text{ s}$$



[Nigam, Saurav, Carrier lifetimes in silicon carbide, PhD Thesis, 2008](#)

I-V performance & simulation



- ◆ The calibration of carrier lifetime could increase the leakage current.
- ◆ The SRH is not dominated term of leakage current.

Bulk Defects G&R to Leakage Current

Recombination

$$R = R_{SRH} + R_{Trap} + \dots$$

$$R_{net} = \frac{N_t v_{th}^n v_{th}^p \sigma_n \sigma_p (np - n_{i,eff}^2)}{v_{th}^n \sigma_n (n + n_1/g_n) + v_{th}^p \sigma_p (p + p_1/g_p)}$$

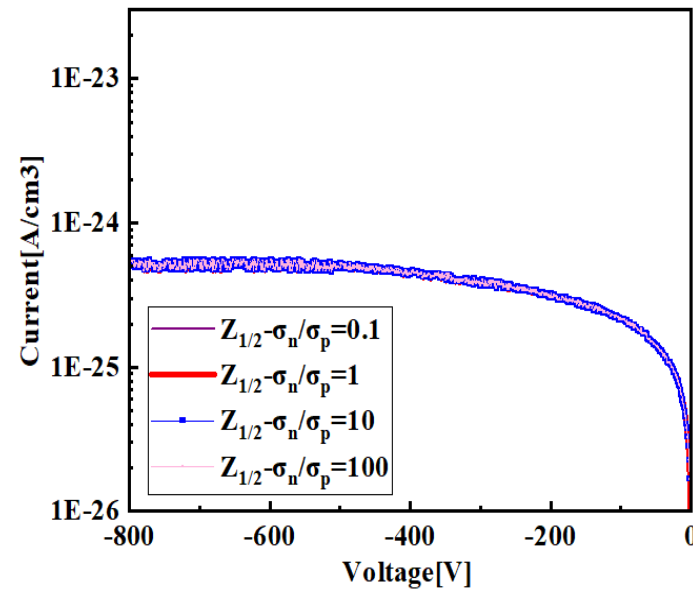
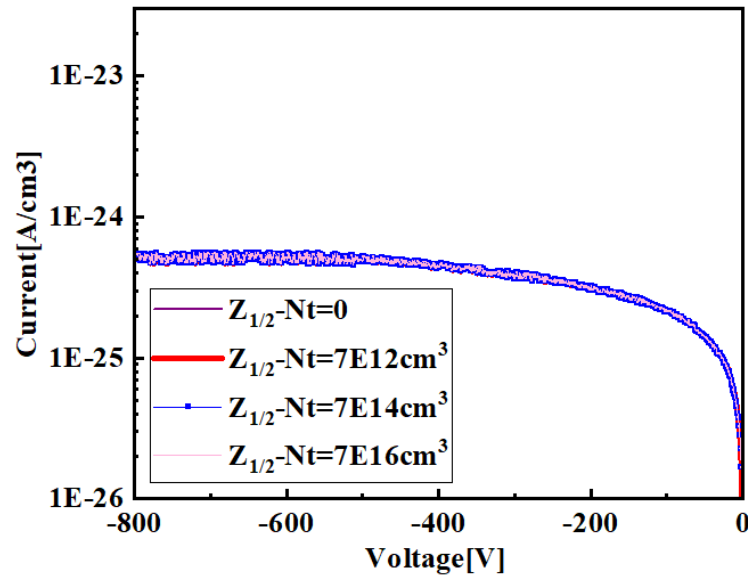
Z_{1/2} electron defects observed by Deep Level Transient Spectroscopy (DLTS)

Trap level	Type	Et (eV)	Nt (cm ⁻³)	σ _{inter} (cm ²)
Z _{1/2}	Electron	0.62-0.68	1e15~1e13	1e-12~1e-16

<http://aip.scitation.org/doi/10.1063/1.114800>

<http://aip.scitation.org/doi/10.1063/1.364397>

<http://aip.scitation.org/doi/10.1063/1.1334907>



- ◆ N_t and σ of Z_{1/2} have no effect on the leakage current
- ◆ σ of Z_{1/2} have no effect on the leakage current

Bulk Defects G&R to Leakage Current

Recombination

$$R = R_{SRH} + R_{Trap} + \dots$$

$$R_{net} = \frac{N_t v_{th}^n v_{th}^p \sigma_n \sigma_p (np - n_{i,eff}^2)}{v_{th}^n \sigma_n (n + n_1/g_n) + v_{th}^p \sigma_p (p + p_1/g_p)}$$

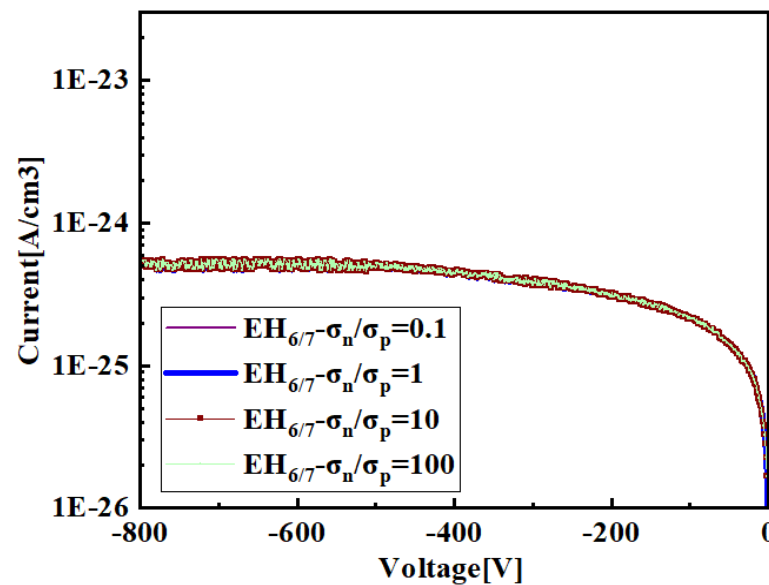
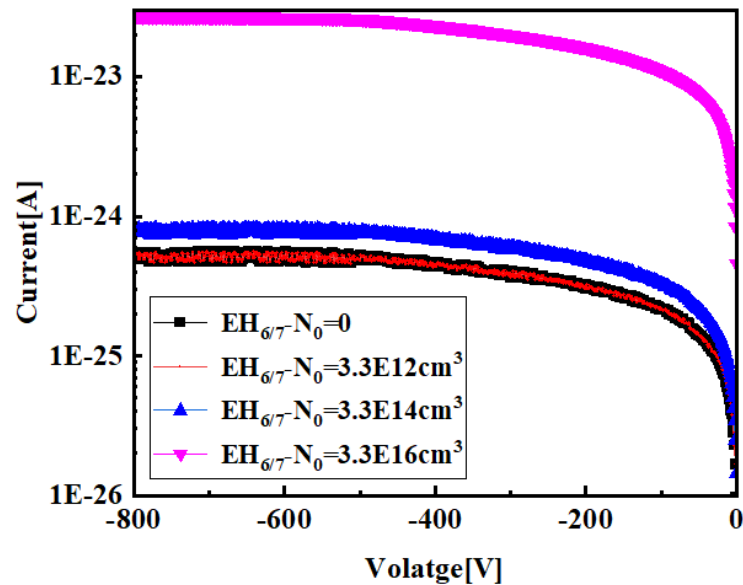
EH_{6/7} electron defects observed by Deep Level Transient Spectroscopy (DLTS)

Trap level	Type	Et (eV)	Nt (cm-3)	σ _{inter} (cm ²)
EH _{6/7}	Electron	1.25-1.73	1e15~1e17	1e-12~1e-15

<https://linkinghub.elsevier.com/retrieve/pii/S0921452699006018>

<http://aip.scitation.org/doi/10.1063/1.1543240>

<http://aip.scitation.org/doi/10.1063/1.2170144>



- ◆ σ of EH_{6/7} have no effect on the leakage current
- ◆ N_t of EH_{6/7} has little effect on the leakage current
- ◆ Deep level defects not the main factor affecting leakage current!

Calibration the leakage current

Macroscopic defects may have a greater impact on leakage current.

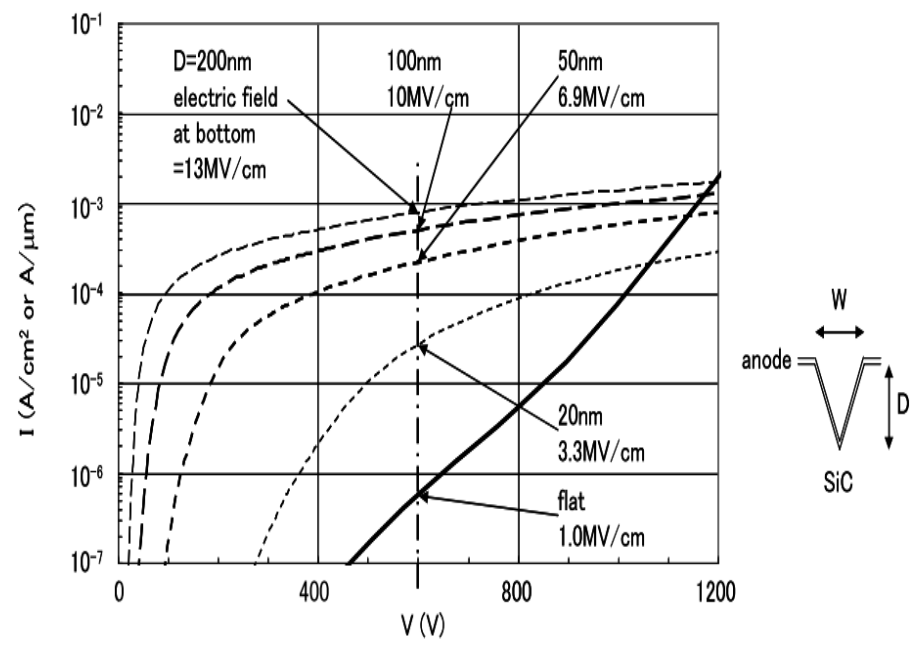
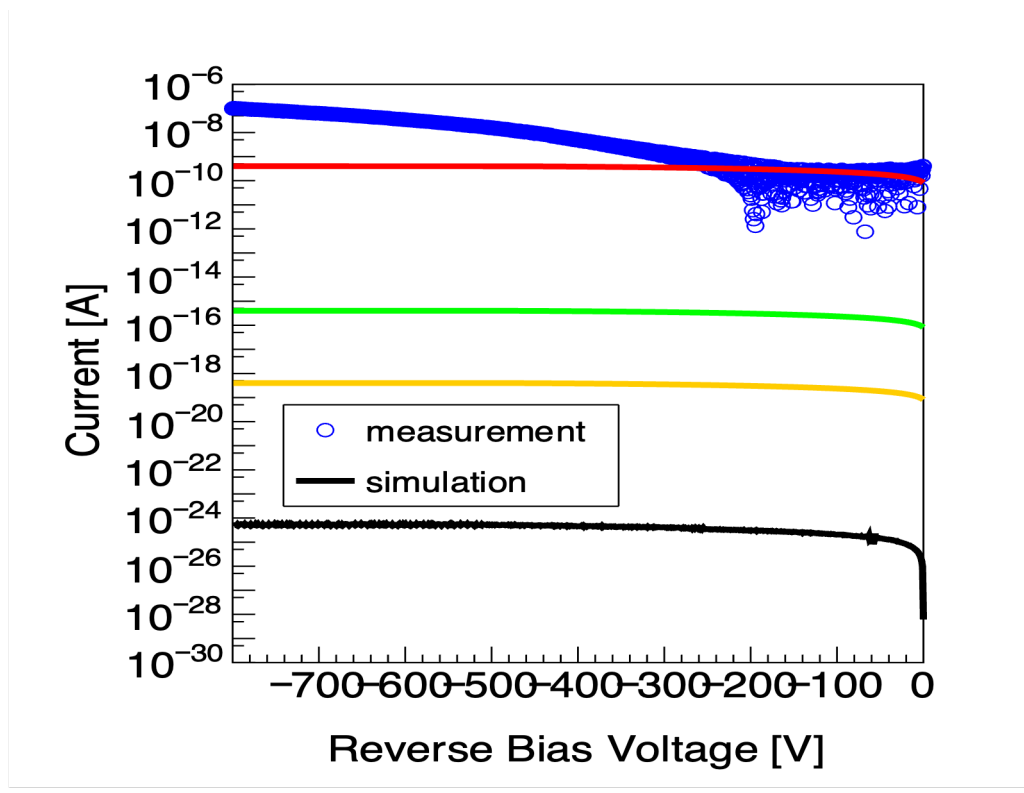


Fig. 3. Calculated current only in portion around macroscopic defects, grooves of W=20nm. The value of electric field is taken at 600V.

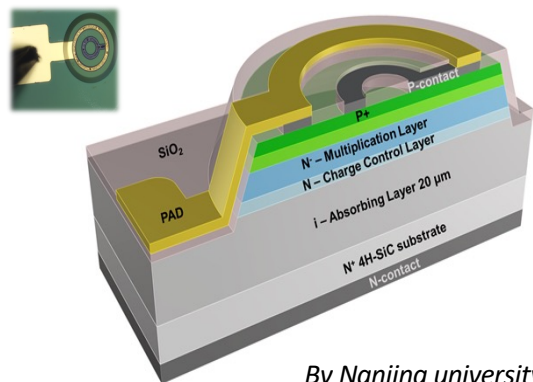
Use constant G&R rate to replace the complex traps effects.

$$R_{net} = \frac{N_0 v_{th}^n v_{th}^p \sigma_n \sigma_p (np - n_{i,eff}^2)}{v_{th}^n \sigma_n (n + n_1/g_n) + v_{th}^p \sigma_p (p + p_1/g_p)} \sim \text{Constant}$$



Constant G&R rate 10^{12} cm^{-3} — Same leakage current level

Prototype Structure of NJU 4H-SiC LGAD



By Nanjing university (NJU)

Fluctuations of process

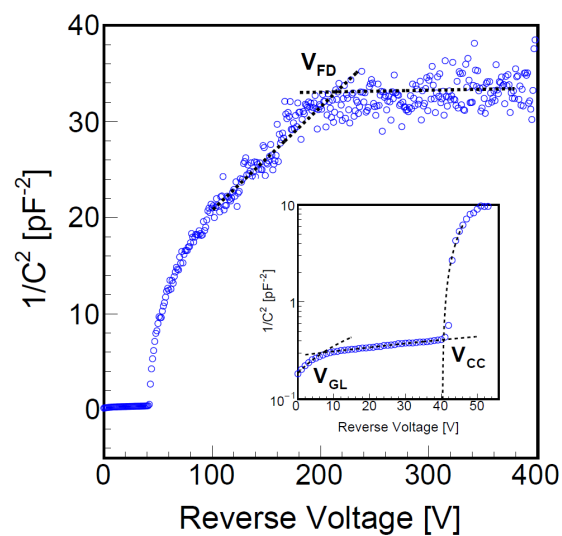
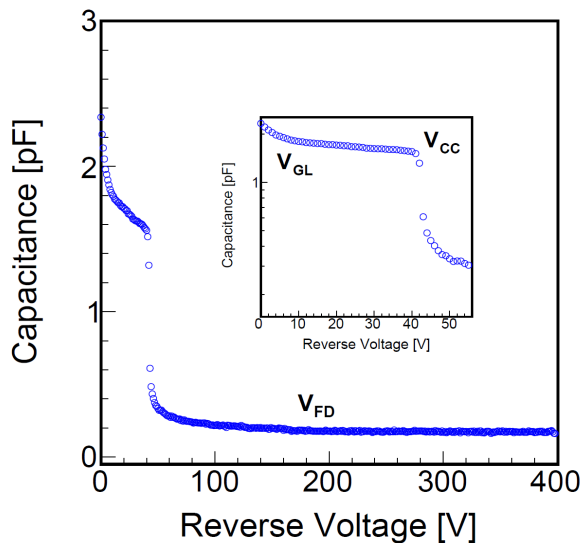
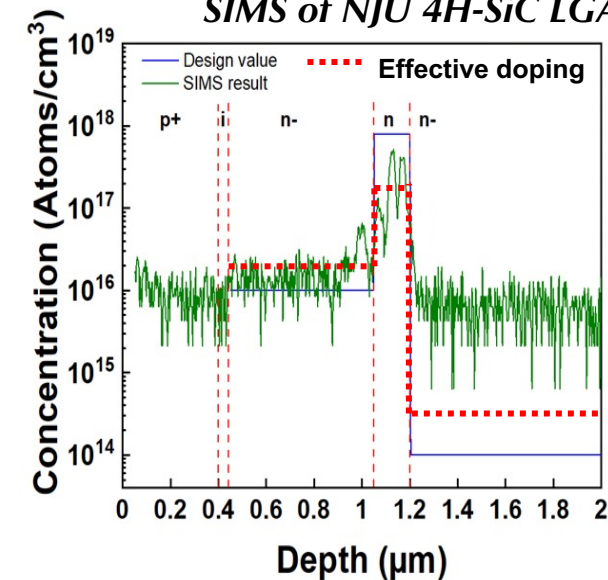
Designed doping

P+ 3e18 0.4μm
50nm i-SiC
N- 1e16 0.6μm
N 8e17 0.15μm
N- 1e14 20μm
N+ Substrate

Effective doping

P+ 3e18 0.4μm
50nm i-SiC
N- 2e16 0.6μm
N 1.7e17 0.15μm
N- 3.2e14 20μm
N+ Substrate

SIMS of NJU 4H-SiC LGAD



◆ The NJU 4H-SiC LGAD could be fully depleted when $U > 200$ V.

V_{GL} : Gain Layer depletion voltage

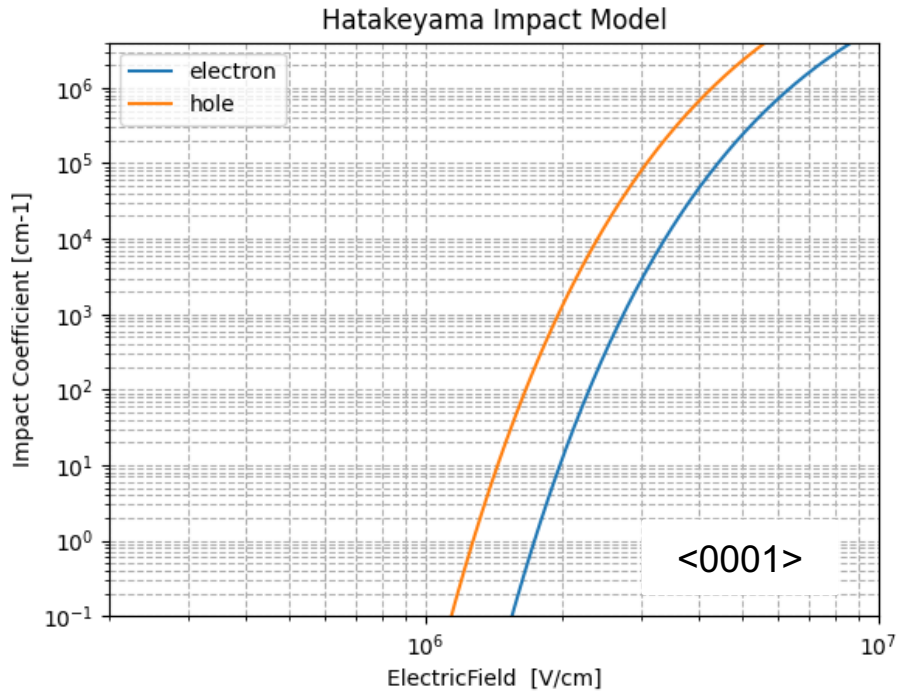
V_{CC} : Charge Control Layer depletion voltage

V_{FD} : Full Depletion voltage

[The 40th RD50 Workshop \(CERN\) Development of 4H-SiC Low Gain Avalanche Diode · Indico](#)

Simulation of NJU 4H-SiC LGAD

- ◆ To simulate the impact ionization of 4H-SiC LGAD, the Hatakeyama avalanche model was selected due to the anisotropic behavior in 4H-SiC devices.



Impact ionization coefficient

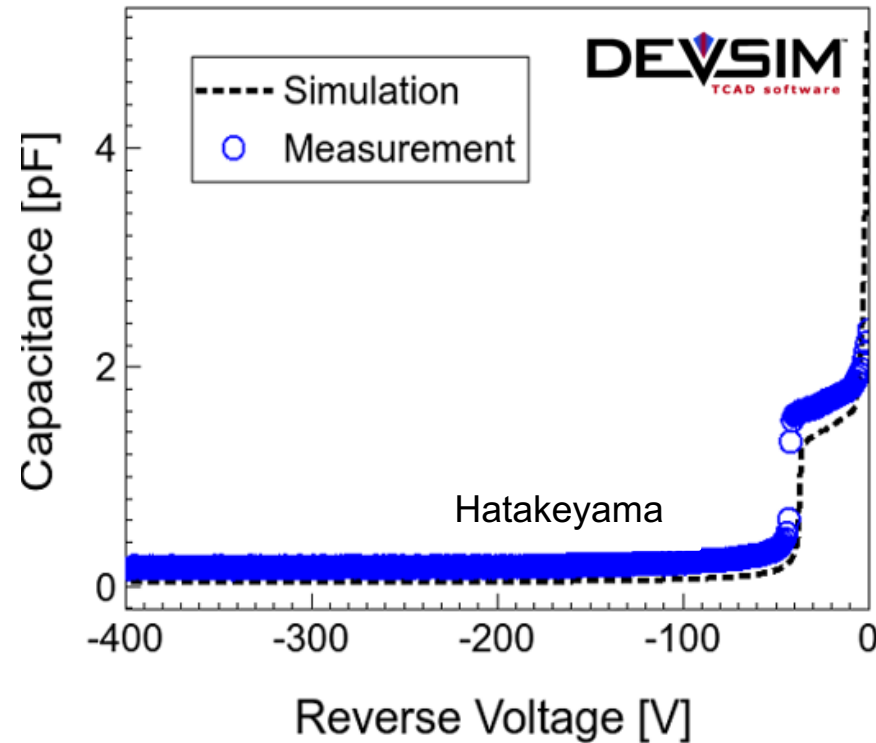
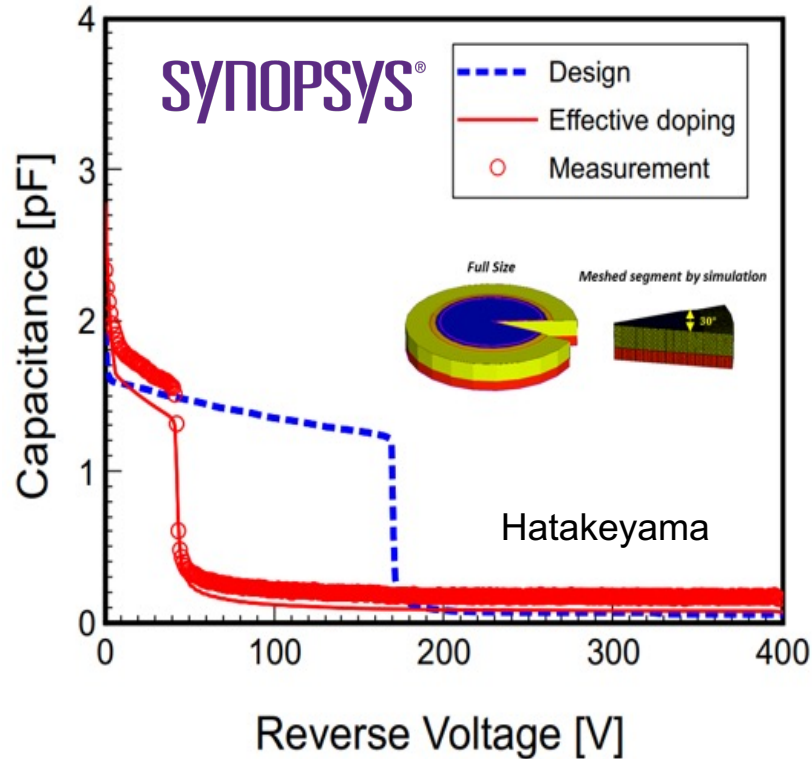
$$\alpha = \gamma a e^{-\frac{\gamma b}{F}}$$

The driving force F is defined as the straight electric field E

symbol	direction	value	unit
a_e	<i>c</i> -axis	1.76×10^8	cm ⁻¹
b_e	<i>c</i> -axis	3.30×10^7	V/cm
a_h	<i>c</i> -axis	3.41×10^8	cm ⁻¹
b_h	<i>c</i> -axis	2.50×10^7	V/cm
a_e	<i>a</i> -axis	2.10×10^8	cm ⁻¹
b_e	<i>a</i> -axis	1.70×10^7	V/cm
a_h	<i>a</i> -axis	2.96×10^8	cm ⁻¹
b_h	<i>a</i> -axis	1.60×10^7	V/cm

From database

- ◆ holes share a greater multiplication rate than electrons
- ◆ The impact ionization of initial holes dominates the carrier multiplication

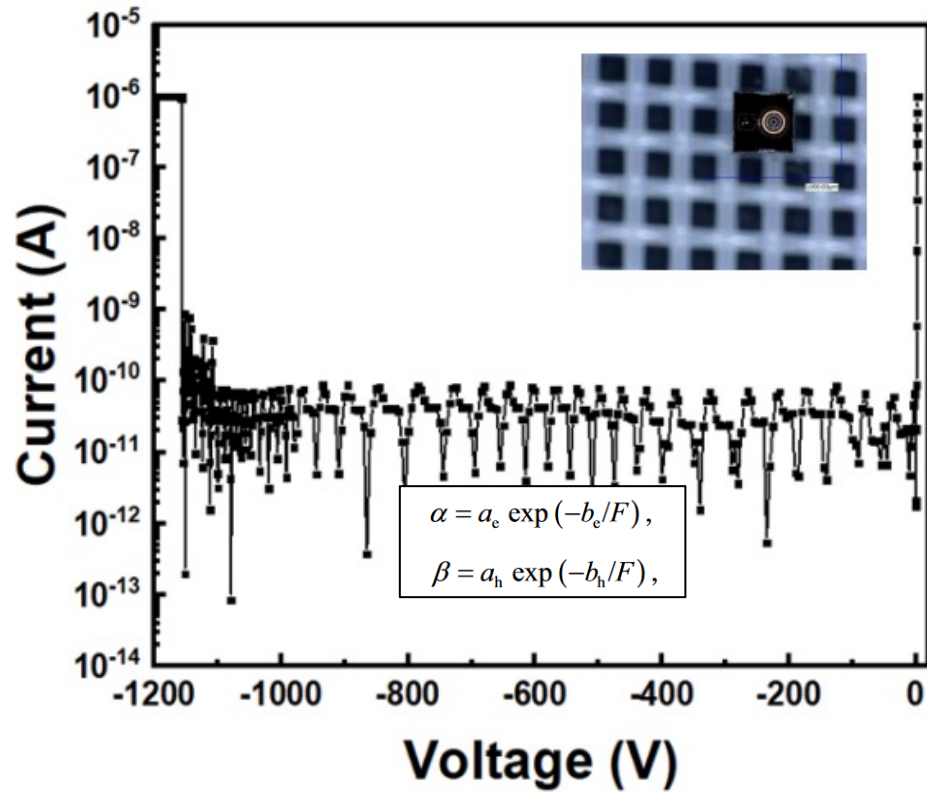


- ◆ A certain gap between the designed doping and the effective doping concentration.
- ◆ The calibrated effective doping concentration selected in simulation (Synopsys/ DEVSIM).
- ◆ **Good agreement between measurement and DEVSIM simulation of C-V for 4H-SiC LGAD.**

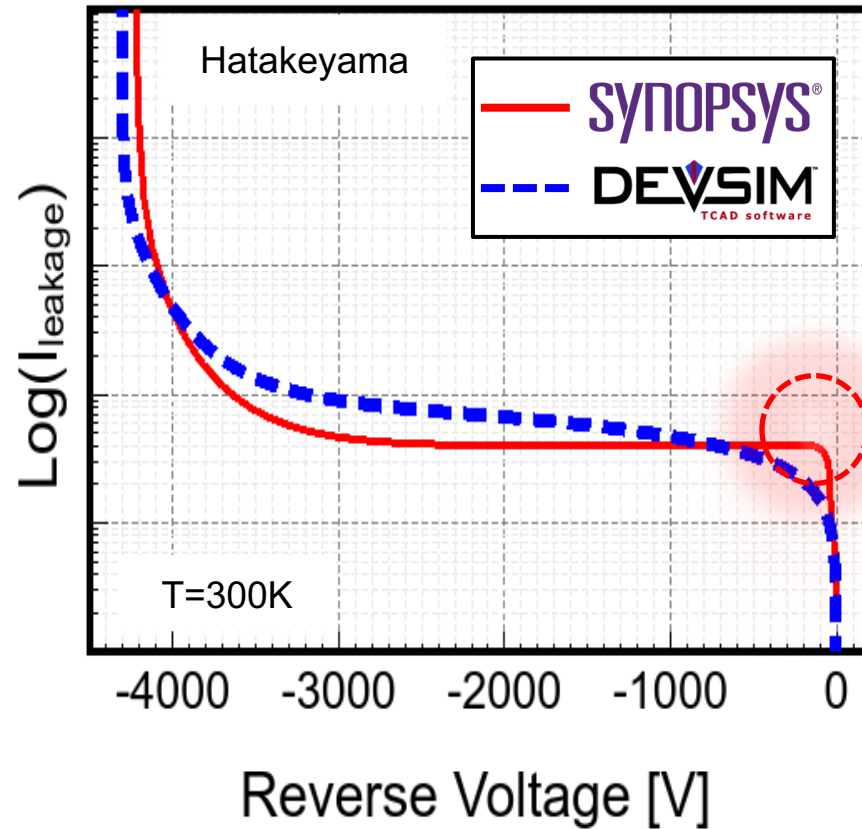
Simulation of NJU 4H-SiC LGAD

Measurement of leakage current

NJU 4H-SiC LGAD



DEVSIM simulation of leakage current



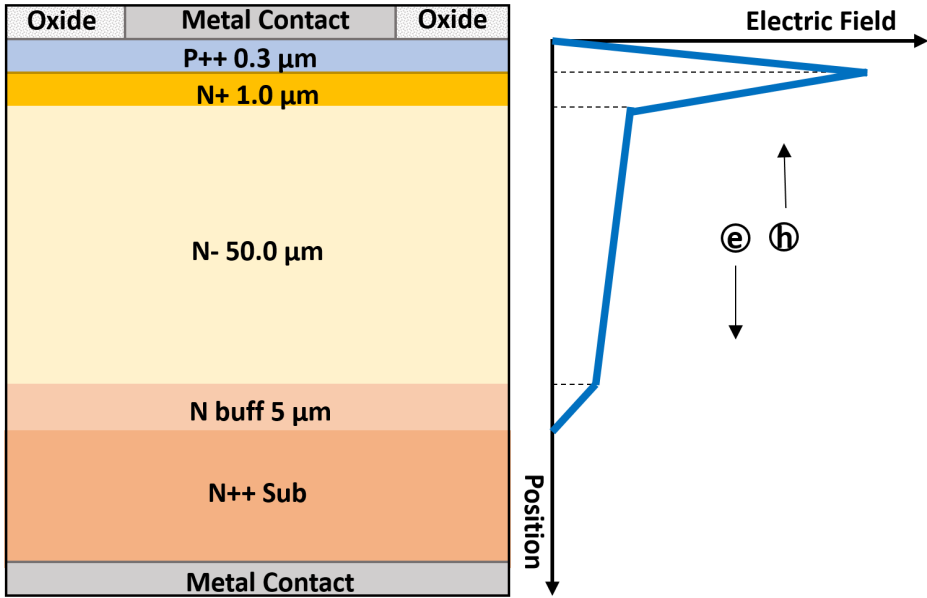
◆ A large discrepancy for V_{BD} .

◆ DEVSIM and SYNOPSIS simulation results at breakdown voltage are consistent

Introduction of SICAR— 4H-SiC LGAD for MIP

◆ SICAR (Silicon CARbide): 4H-SiC device for MIPs

- Improve low gain issue of NJU
- Independent designed by RASER team [1]
- Fabricate the 4H-SiC LGAD
- Prototype of SICAR1

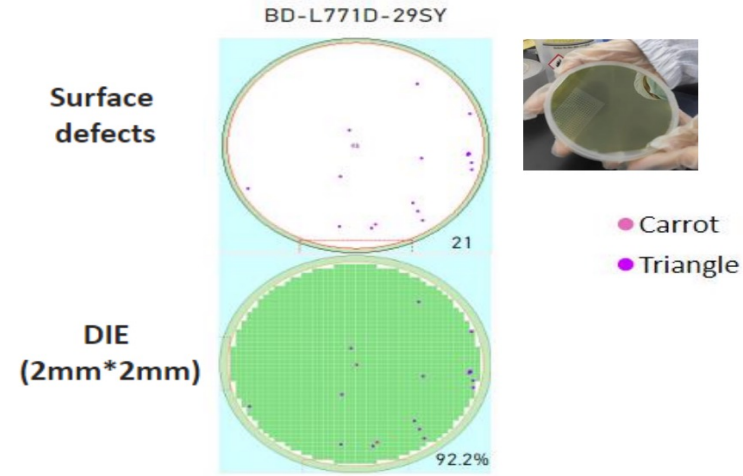


Structure of SICAR1

Design of SICAR1

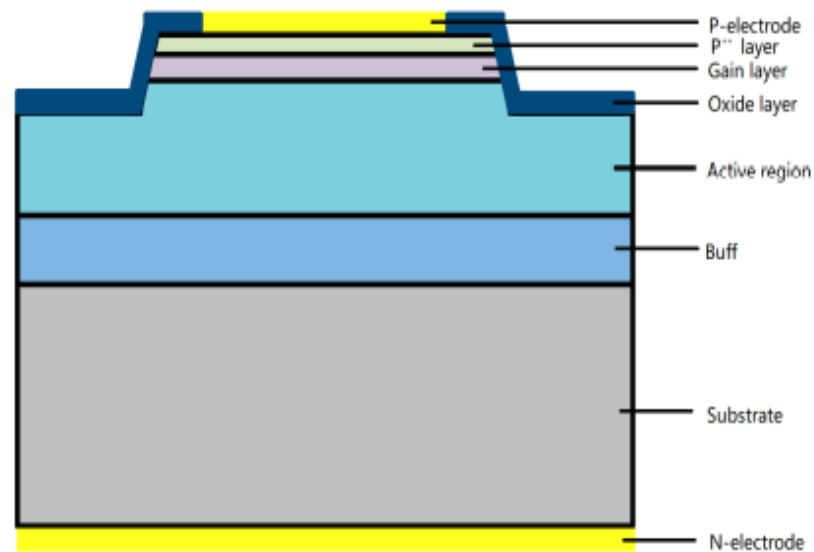
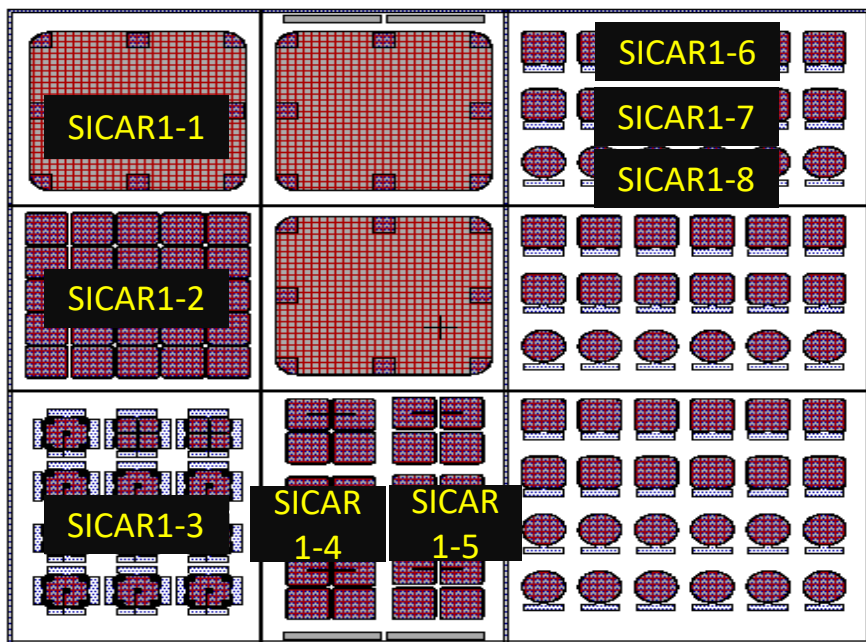
Epi structure	Thickness [um] (Design)	Doping [cm ⁻³] (Design)
P++	0.3	2e19
N+ (gain layer)	1.0	1e17
N- (active layer)	50.0	1e14
N buff	5.0	1e18

Distribution of defects



[1] RASER -

Lithography mask



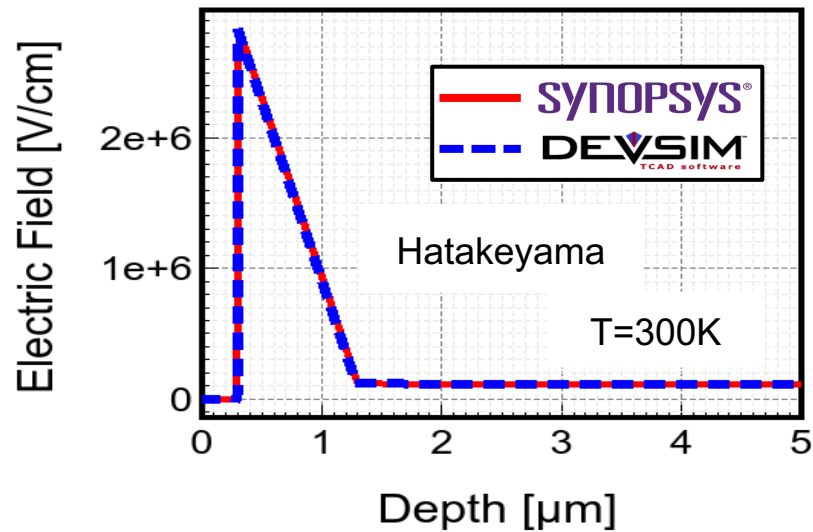
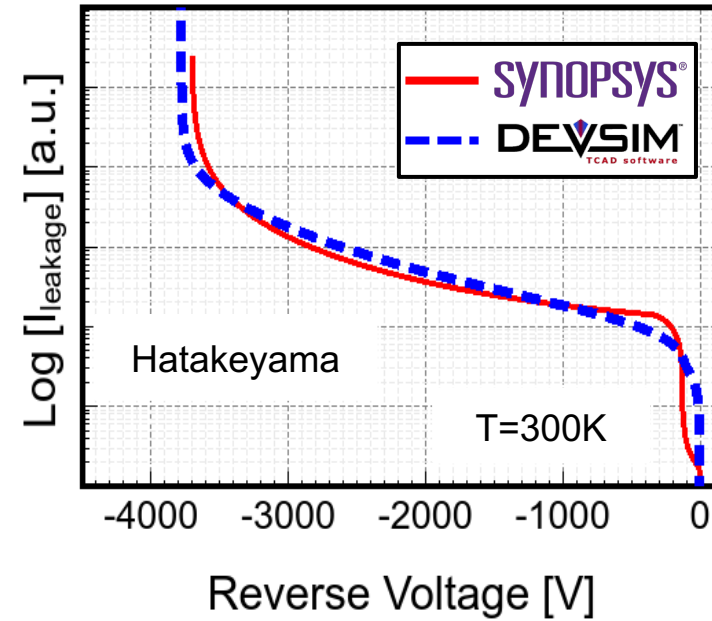
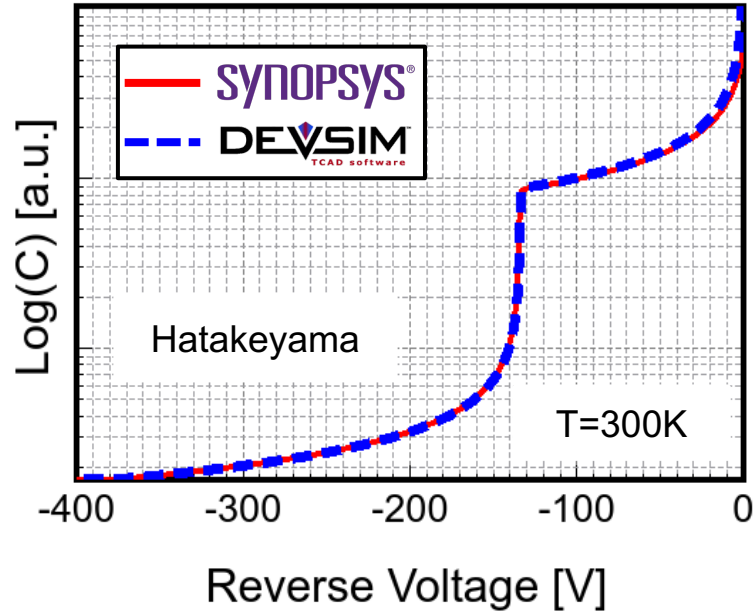
Final structure

Name	Type	Size ($\mu\text{m} \times \mu\text{m}$)	Corner Radius(μm)
SICAR1-1	Single	5000 x 5000	500
SICAR1-2	5x5	1000 x 1000	100
SICAR1-3	Single	1000 x 1000	100
SICAR1-4	2x2	1000 x 1000	100
SICAR1-5	2x2	1000 x 1000	100
SICAR1-6	Single	1000 x 1000	100
SICAR1-7	Single	1000 x 1000	200
SICAR1-8	Single	1000 x 1000	500

鷓

- ◆ Different device size correspond to different requirement
- ◆ Processing is in progress...

Simulation of SICAR1



◆ Good agreement between the DEVSIM and SYNOPSIS simulation

DEVSIM Simulation:

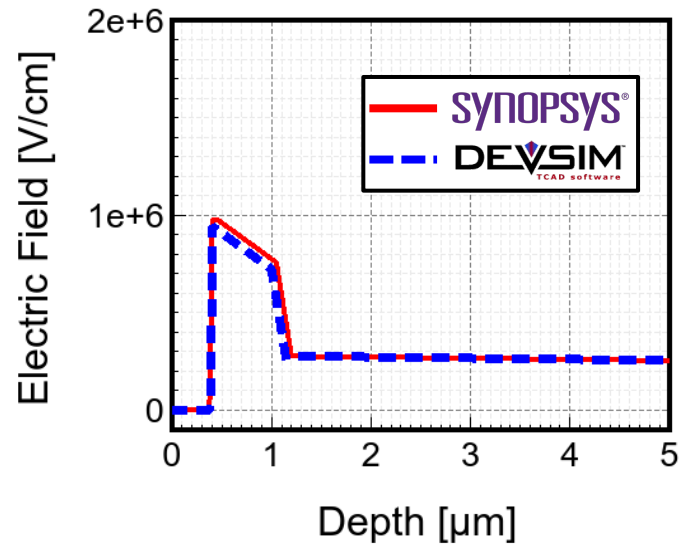
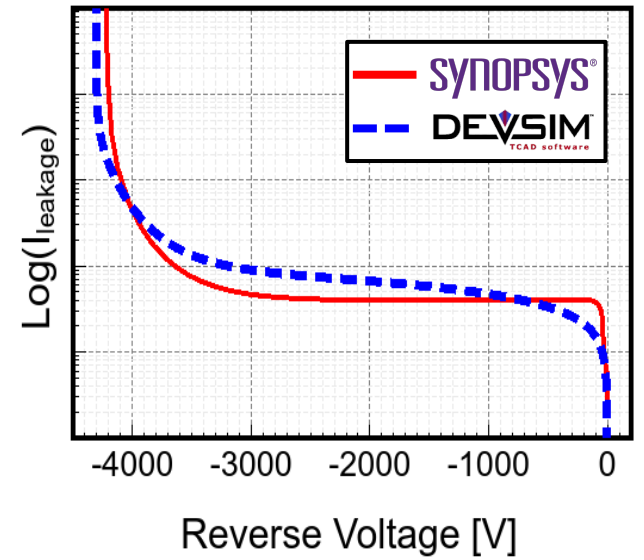
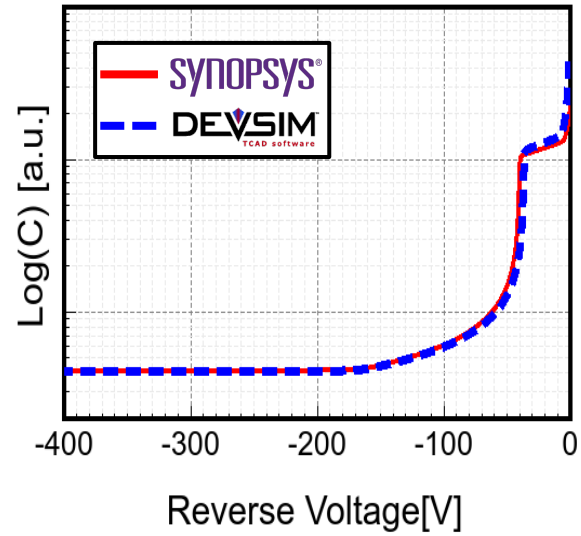
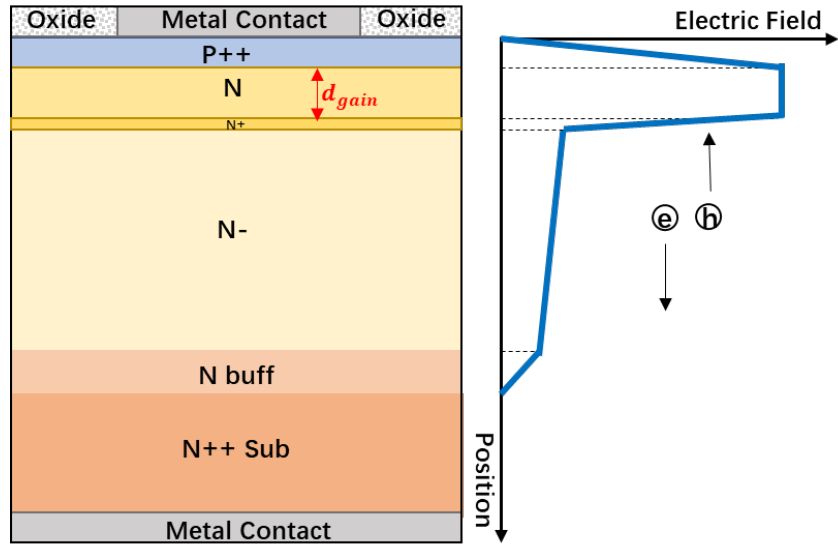
1. Good agreement between measurement and DEVSIM simulation for 4H-SiC PIN.
2. Deep level defects aren't the main factor affecting the leakage current.
3. Good agreement between the DEVISM simulation and SYNOPSIS simulation of the 4H-SiC LGAD.

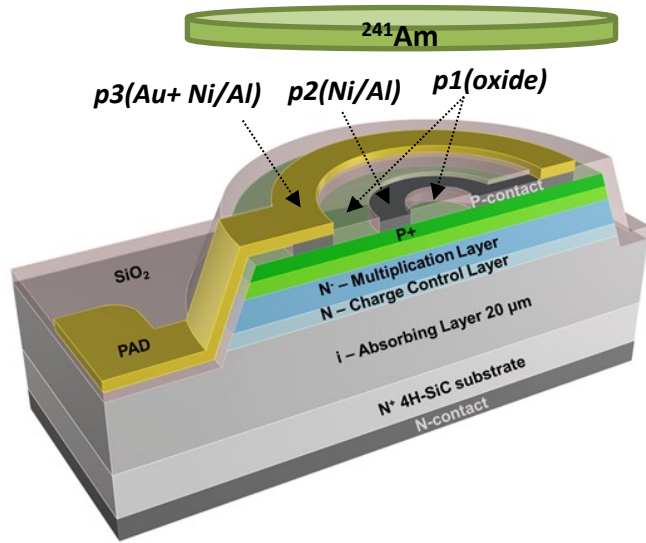
NEXT:

1. Independently develop the 4H-SiC LGAD (SICAR)
2. Combine the macroscopic defects in DEVSIM to calibrate the leakage current.
3. Calibrate the breakdown voltage of the 4H-SiC LGAD.

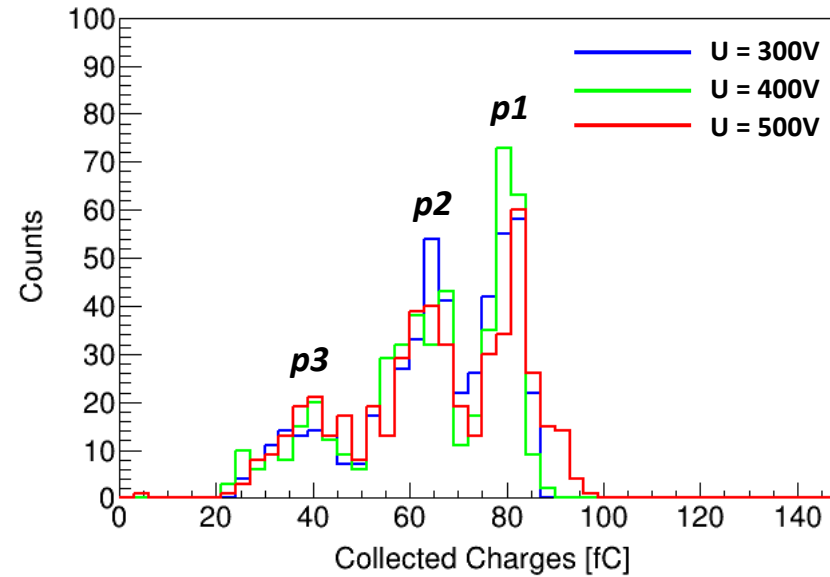
Thanks for your attention!

Backup

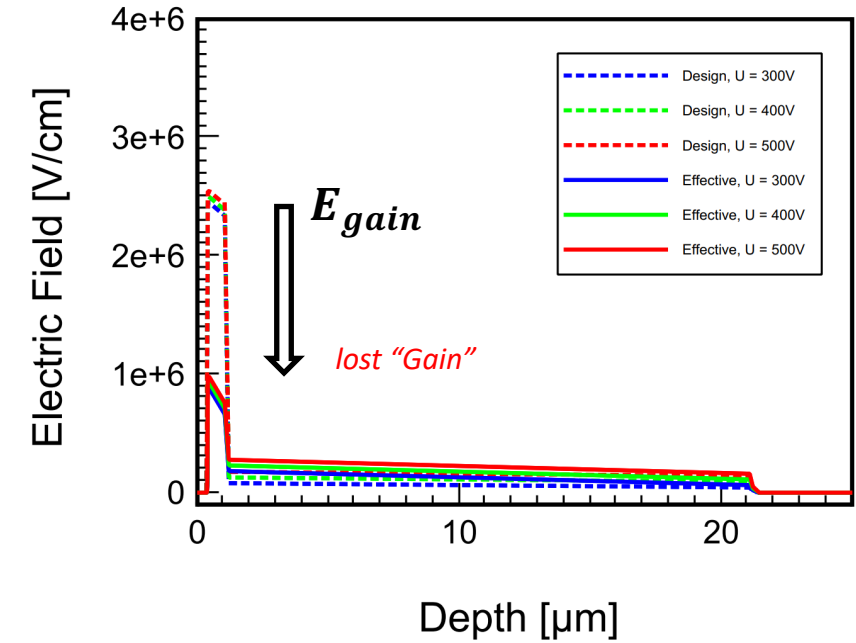




Collected charges spectrum for v2



Simulated electric field for v2



➤ No collected charges increasing by increase of voltage. -> No gain observed that agrees with the simulation by effective doping.